Ref #	Hits	Search Query	DBs	Default	Plurals	Time Stamp
L1	66160	CMP or "chemical mechanical polishing"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	Operator OR	ON	2006/01/20 15:05
L2	2319275	wafer or substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:05
L3	14231	"polishing pad"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:05
L4	14769	remov\$6 adj rate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:05
L5	2241	conditioning near4 pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:05
L6	1387838	calculate ot calculated or calculating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:05
L7	640	L1 and L2 and L3 and L4 and L5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:05
L8	140	L7 and L6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:20
L9	2	("6093080").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/20 15:30
L10	5	("5036015"   "5639388"   "5743784"   "5904608"   "5904609").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/20 15:22

L11	16	("6093080").URPN.	USPAT	OR	ON	2006/01/20 15:25
L12	4343	((438/689) or (438/691) or (438/692)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/20 15:25
L13	1	12 and (pad near wear) and ((condition or conditioning) near model)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:33
L14	3103	12 and (CMP or polishing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:33
L15	1957	14 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:33
L16	330	15 and (model or recipe)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:33
L17	11083	(polish or polished or polishing or CMP) near8 (substrate or wafer) near8 (pad or bond)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:34
L18	71	(condition or conditioning or conditioned) near8 (pad or bond) near8 (model or recipe)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:35
L19	10	(17 and 18).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/20 15:35